Qualcomm, a world leader in mobile technologies, offers the new Snapdragon 820, a complete chipset currently powering or in-development with more than 100 smartphones worldwide. The U.S. versions of Samsung’s latest flagship phones, the Galaxy S7 and Galaxy S7 Edge, integrate the Snapdragon 820 chipset. In this chipset, we discovered for the first time a Qualcomm component featuring Fan-Out Wafer-Level Packaging (FOWLP): the Qualcomm Audio Codec WCD9335.

Located on the smartphone’s main board, the audio codec chip’s presence in the Samsung Galaxy S7 and S7 Edge depends on the smartphone version. The international version, featuring an Exynos chipset, integrates the audio codec chip from Cirrus Logic. The U.S. version, featuring the Snapdragon 820 chipset, integrates the audio codec from Qualcomm.

The Qualcomm WDC9335 is wafer-level packaged with fan-out technology. This is still relatively rare in the smartphone market but is expected to spread quickly. The FOWLP technology used is the eWLB, licensed by Intel/Infineon to several OSATs including ASE, Nanium, and STATS ChipPAC.

Thanks to this FOWLP process, Qualcomm is able to propose a very small die independent of the area required by the I/O pads. The result is a very cost-effective component that can compete with a standard fan-in WLP technology.

This report includes a comparison with the audio codec solution from Cirrus Logic for the international version, which uses a standard fan-in WLP technology. It also features comparisons with FOWLP technologies like RCP from NXP/nepes, and eWLB 1st-generation from Infineon.

Title: Qualcomm WCD9335 Fan-Out WLP Audio Codec
Pages: 93
Date: April 2016
Format: PDF & Excel file
Price: Full report: EUR 3,290

COMPLETE TEARDOWN WITH:
• Detailed photos
• Precise measurements
• Material analysis
• Manufacturing process flow
• Supply-chain evaluation
• Manufacturing cost analysis
• Estimated sales price
• Comparison with Cirrus Fan-In WLP Audio Codec in Samsung S7 European Version
• Comparison with Intel/Infineon’s eWLB & NXP/nepes RCP
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Analysis performed with our costing tools 3D Package CoSim+ and IC Price+

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Author: Stéphane Elisabeth
Dr Stéphane Elisabeth has joined our team this year. He has a deep knowledge of Materials characterizations and Electronics systems. He holds an Engineering Degree in Electronics and Numerical Technology, and a PhD in Materials for Microelectronics.

Author (Lab): Yvon Le Goff
Yvon Le Goff has joined System Plus Consulting in 2011, in order to set up the laboratory of System Plus Consulting. He previously worked during 25 years in Atmel Nantes Technological Analysis Laboratory as fab support in physical analysis, and 3 years at Hirex Engineering in Toulouse, in a DPA lab.
The new 77 GHz Radar Chipset for ADAS from NXP/Freescale - SiGe:C xHBT technology & Fan-Out RCP Wafer-Level Packaging.

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